DAIKIN MALAYSIA GROUP SCHOLARSHIP PROGRAM CHECK LIST

Full Name of Applicant (as per I/C):	
Contact No (House):	
(H/P):	
Email Address:	

Please attach this **CHECKLIST** as the front page together with other documents in the following order:

- a Check List
- b Scholarship Application Form
- c Supporting Documents Listed As Follows:

Have you submitted the following documents?

Please tick ($\sqrt{}$)

1	Application Form	
2	Identity Card photocopy	
3	School Leaving Certificates photocopy	
4	School Testimonials photocopy	
5	University Acceptance / Offer Letter photocopy	
6	Academic Calendar (for the degree courses) photocopy	
7	Statement of Course Fees from Bursar of University photocopy	
	Academic result (Photocopy):	
	*A.) University Academic Result (Only applicable for first year student)	
8	B.) SPM/ SPMV	
	C.) STPM/ Matriculation/ 'A' Level/ UEC/ Foundation/ 'O' Level	
	D.) MUET/IELTS/1119/TOEFL	
9	Parents' Identity Card photocopy	
10	Parents' proof of income for the past 2 years - Tax Assessment / EA photocopy	
11	Parents' Salary Slip for the past 3 months photocopy	
12	Disability Card / OKU Card photocopy (if available)	
13	Disability Card / OKU Card - Physically Challenged Family Member photocopy (if available)	
14	Certificates of Co-Curriculum Activities photocopy	
	Others (if any)	
	Please state:	
15		
16	All the certificates are certified by Principal/ Faculty Dean/ Department of Student Affairs	

Kindly ensure all required documents are attached. Incomplete documents submission might not be processed.



DAIKIN MALAYSIA GROUP SCHOLARSHIP PROGRAM APPLICATION FORM

PASSPORT SIZE PHOTO	

										L			
ersonal Details													
Full Name (as per IC)] [rital itus			
Nationality Mobile No								Home Tel No					
Email Address													
Residential Address	Post	code:			State:								
	1 030	couc.			Tertiary Edu	ootion D	otoile						
University / Colleg Course Name Course Duration	e Name	:			Tertury Edu	cution D	Cuins						
					Family	Details							
		Fath	ier						M	other			
Full Name (as per IC)						Full Name (as per IC)							
NRIC No.						NRIC No	No.						
Age						Age							
Residential Address	Post code:		_ State:			Residential Address Post code:State:							
House Phone No						House Phone No							
Mobile No						Mobile No							
Occupation						Occupati	on						
Working Status	Working Full Time		Not Working Part Time		Retired	Working	Status	Working Full Time			orking Time		Retired
Name of Employer					•	Name of	Employer						
Address of Employer Telephone No				Address	Address of Employer Telephone No								
	Fax No					L		Fax no					
3(a) Household In				`									
3(b) Annual Gross Income of Parents (Latest Year) Father (RM)							λ.	Iother (R	M)			Tota	l (RM)
Employment				rau	ici (KWI)		IV.	iomer (K	171)		-	rota	i (KWI)
Business		-									+		
Rental											1		
Others		-									+		
											+		

3((c) Family Expendit	ure											
		Types	of Expen	diture					Monthly	(RN	1)		
	House Installment / Rental												
	Food												
	Electricity / Water	r											
	Telephone												
	Loan Repayment	(car / moto	r-bike / ap	pliances / e	etc)								
	Transportation												
	Education												
	Others (Please spe	ecify)											
			Total										
					Sil	olings Iı	nformati	on					
	Full Name	Age	Gender	nder Relationship			ai G	cupation / rade (if Study)	Company / School / Institution		1/	Monthly Income (if working)	
	a) Has/have any of	-		rently/prev	viously re	ceived a	any Scho	larship?		Y	es]	No
5(b) If YES, please sta	te the follo	owing:		Siblings'	Scholar	shin Inf	ormation					
	Full Name		Name of	Organizat	_		Course N		Total Amount	Don	Annum	Co	ourse Duration
	r un ivame		In	Institution			Jourse	ame	Total Amount Let Amount			-	(Years)
Dl		7il M	(4:-	-1:1:4 4:		_:	IE AN	v					
rny	ysically Challenged F Full Na	•	noers (dis	Age		lationsl			ness/Impairs			Du	ration
-									-				
								I					
	you have any siblinges, please give the de	_	ves who a	re serving	under Da	nikin Ma	alaysia G	Froup?			Yes]	No 🔲
	Name (as pe			Contact	No.	Relati	onship	Name	of Company	f Company Posit			Years of services
													SCI VICES

	Extra-Curricular Activities (Secondary School Onwards)												
	No	Associations / Soci	ieties / Club / Sp	ort	From (Y	ear)	To (Year)	Posit	ion Held				
	1												
	2												
	3												
	5												
*		e do not state position held in	n Associations /	Societies / Club /	Sport if no	document i	is provided.						
	Awards (Secondary School Onwards)												
	No	No Award(s) and Details Year Levels / Grade											
	1												
	2												
	3												
	5												
					al Conditi	ons							
)	10(a)	Any physical disability (e.g. s		eech)?									
		YES Please	e state:			-							
	10(b)	Please quote Disabled (OKU) Identification C	ard number (whe	re applicable	e):							
		Disabled (OKU) Identification	on Card number:			_							
	10(c)	Any previous illness / surgery YES Please	y? e state:										
		NO Please	state.			•							
	10(d)	Any current illness?											
		YES Please	e state:			-							
				Worki	ng Experie	ence							
ı		Name of Company	Position	Date J From	oined To	Last D	rawn Salary	Reason o	f leaving				
				Fion	10								
1													
					Referees								
	**NC	TE: NOT YOUR RELATIV	VES. PREFERA			S) / TEACH	IER(S)						
2	Give '	TWO referees that are not rel	ated to you, who	may attest to your	achieveme	nts and qual	ifications:						
	No	Name Contact No. Employer Name Occupation Relationship Know											

		Others								
3 13(a)	Were you a scholarship recipient before?				YES	NO				
13(b)	Are you RECEIVING any financial assistance or sponsorsh or foundation?	ncial assistance or sponsorship from other organization, institution, fund YES								
	If YES, please give details:									
	Institution/Fund/Organization/Foundation (e.g. JPA PETRONAS, PTPTN, etc.)	A, MARA,	Duration of From	Sponsorship To	Amount Per Annum (RM)	Bond Period (if any)				
	1)									
	2)									
	3)									
13(c)	Are you currently APPLYING any financial assistance or sp foundation? If YES, please give details:	oonsorship from	other organiza	ation, institution	n, fund or YES	NO				
	Institution/Fund/Organization/Foundation (e.g. JPA	. MARA.	Duration of	Sponsorship	Amount Per	Bond Period				
	PETRONAS, PTPTN, etc.)	-, ,	From	То	Annum (RM)	(if any)				
	1)				(24.12)					
	2)									
	3)									
13(d)	Have you applied for Daikin Malaysia Group scholarship be	fore?			YES	NO				
13(e)	Were you the recipient of the Daikin Malaysia Group scholar	rship before?			YES	NO				
13(f)	off) Are you willing to serve an employment bond within any subsidiaries of Daikin Malaysia Group upon successful completion of studies?									
12(a)	Are you willing to be an intern student under any subsidiarie	s of Doilsin Mal	avcia Group d	uring samastar l	break? YES	NO				
13(g)			-	uring semester	oreak: TES	NO.				
14 Tell	Bri us why are you interested in getting the Daikin Scholarship? (i	ef Explanation in not more than								
		Declaration								
5 Decl	aration of School / College / University									
15(a)	I hereby confirm that the applicant as mentioned above has g	given the correct	and accurate	information.						
15(b)	I hereby confirm that the applicant is our school student.									
	NAME Principal / Faculty Dean / Dept of Student Affairs SIGNATURE Principal / Faculty Dean / Dept of Student Affairs Principal / Faculty Dean / Dept of Student Affairs University Stamp									

☐ NO

YES

Date of Interview

Awarded